MICROSYSTEMS ENABLED PV

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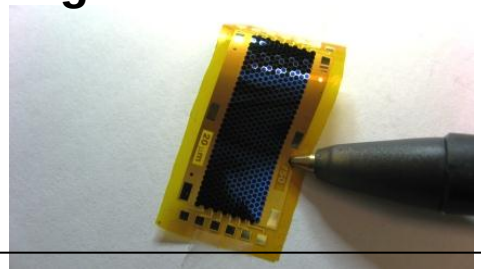
OUTLINE

- **Technology benefits**
- Process flow/assembly examples
- Cost analysis
- From R&D to commercialization
- 3DIC/hybrid assembly and new functionality

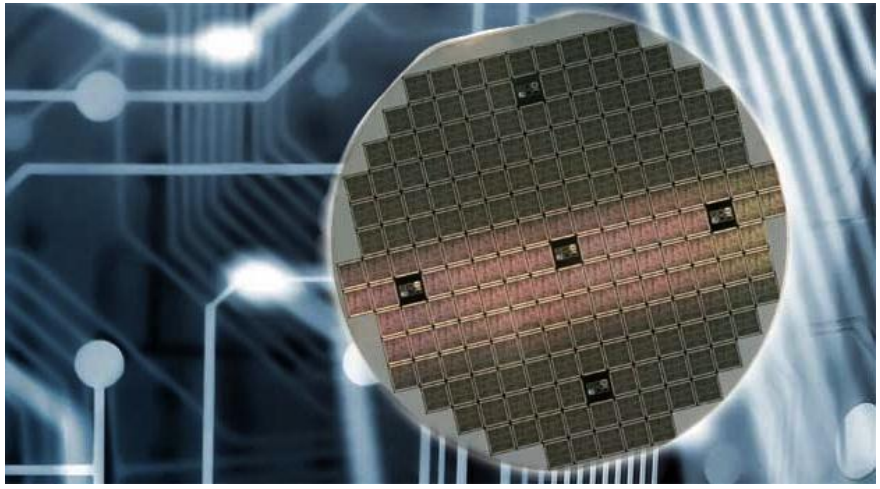
MEPV CORE COMPETITIVE ADVANTAGE

MEPV leverages concepts and technologies from existing successful microelectronics industry (IC, MEMS, LED, LCD, etc.):

- Take advantage of beneficial scaling effects
  - Improved performance
  - Reduced cost
  - New functionality
- Parallel vs. serial manufacturing
- Increased integration - system vs. cell (component) paradigm
- Utilize established manufacturing supply chain and infrastructure (reducing CapEx)

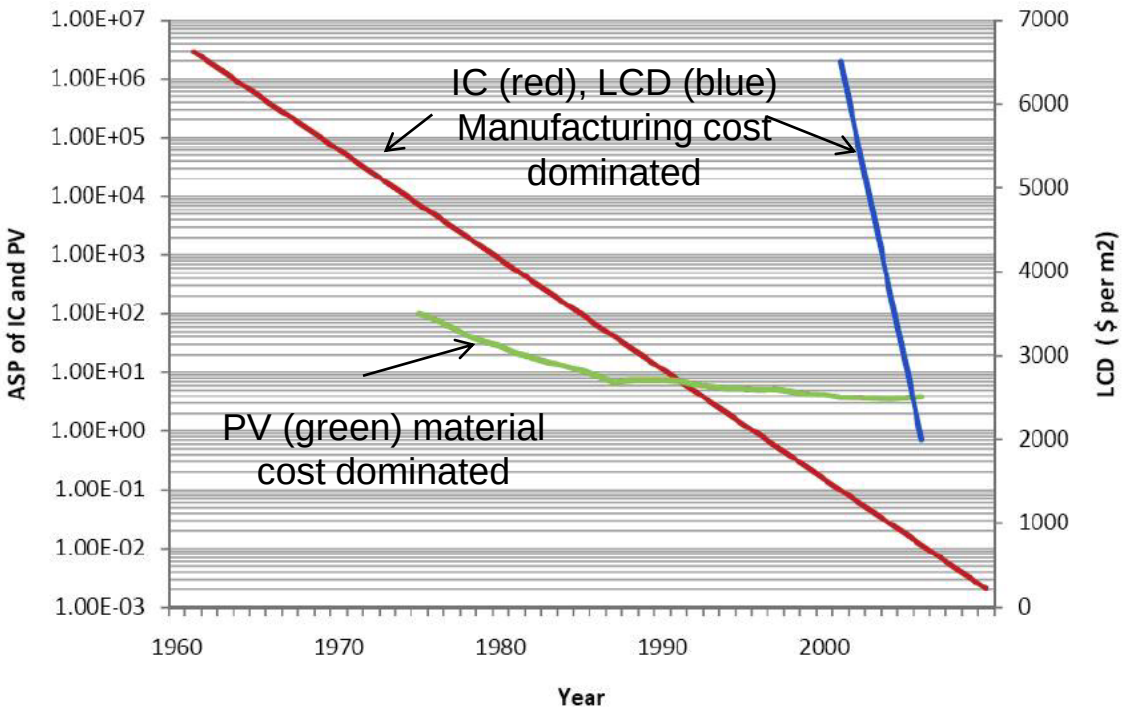


No other PV technology benefits from similar industry synergies



- *Integrated Circuit Market Size: $300B*
- *LCD Market Size: $102B*
- *LED Market Size: $12.5B*
- *MEMS Market Size: $10B*

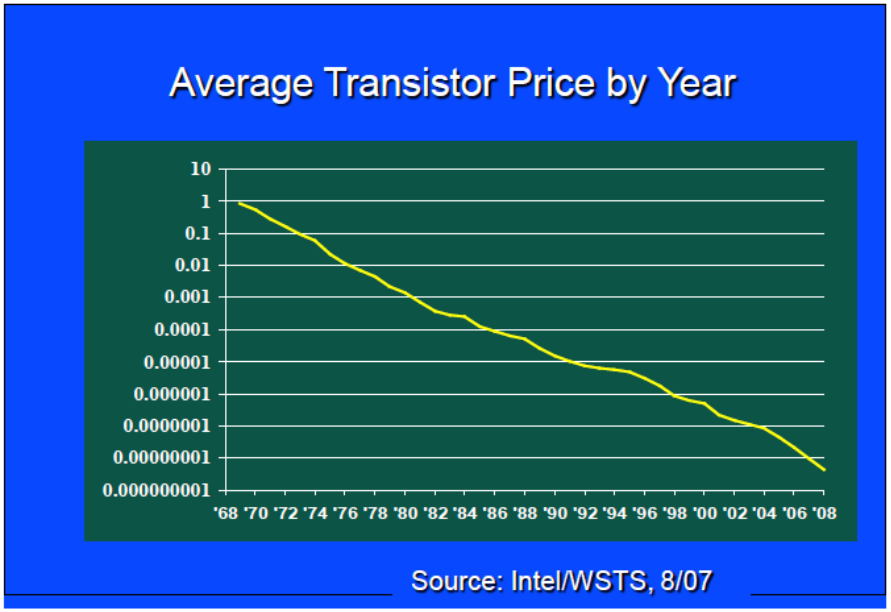
Potential for Cost Reduction



Future cost reductions are much more likely for MEPV than wafered silicon PV since manufacturing costs are a much larger component of the module costs relative to material costs. (Typically manufacturing costs are driven down more rapidly than materials costs.)

Rajendra Singh, "Why silicon is and will remain the dominant photovoltaic material," Journal of Nanophotonics, vol. 3, 032503 (2009), p. 4.

Manufacturing Tools Have Driven ~500x Price Reductions in Processed Silicon



- In 1975, the average price per transistor was ~$0.02 (4-μm features).
- In 2008, the average price per transistor was ~$5x10^{-9} (45 nm features)
- This is a 4,000,000x reduction in cost
  - Device scaling accounts for ~8,000x cost reduction ($/transistor)
  - ***Manufacturing efficiencies account for ~500x reduction in the price of processed Silicon.***

Andrew Hawryluk, DOE Manufacturing workshop on LEDs, San Jose, CA April 2010

Scalability

Established Polysilicon supply (9-9s purity)

2010 >100,000 metric tons (Hemlock, Wacker, REC, MEMC)

2011 >120,000 metric tons

2012 - OCI (S.Korea) – 62,000 metric tons
GCL Poly (China) – 65,000 metric tons
world total > 200,000 metric tons

[Bloomberg Energy Finance]

Standard Si wafered PV
~ 5-6 grams Si/W_{peak}

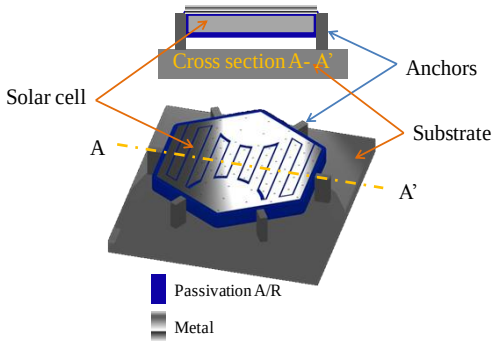
MEPV - < 0.1 gram Si/W_{peak}
Silane/TCS main feedstock
10x thinner cells
no kerf loss (usually 50% for standard Si PV)
>10x optical concentration

200 MW_p/year unit line

- Small IC Fab: 5,000 8'' wafers/week
  (@30 wfr/hr, IC industry standard = 60 wfr/hr)
- 10 pick-and-place tools: 130,000 parts/hr
- 2,900 m^2 PV modules produced per day
  (0.7 acres)
- 200W x 2,900 = 0.58 MW_p/day

Scalability > 100GWp/year
US generation capacity ~1TW

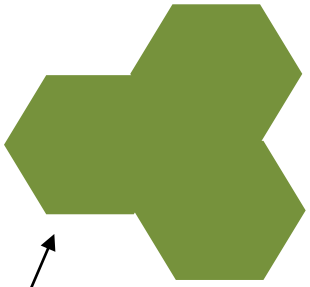
Solar Cell Fabrication: Suspended Cells

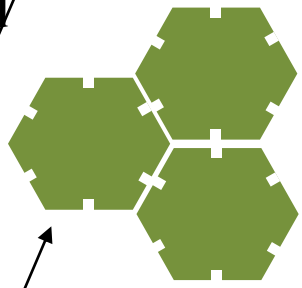


A) SOI cell with nitride and oxide

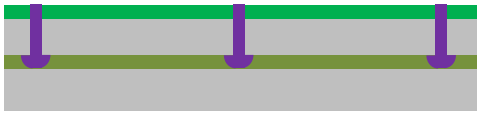
B) First deep etch reaching the BOX layer

C) wet etch to reach the handle wafer

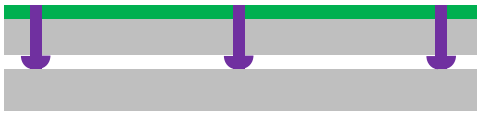




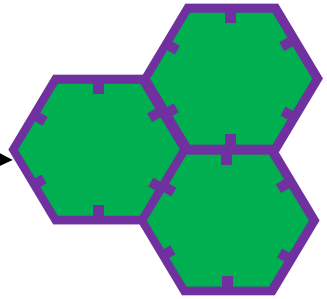
D) polysilicon fill

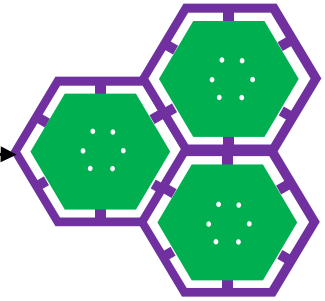


E) Chemical mechanical polishing

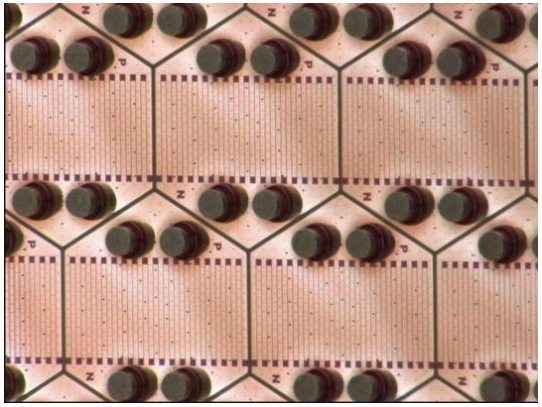


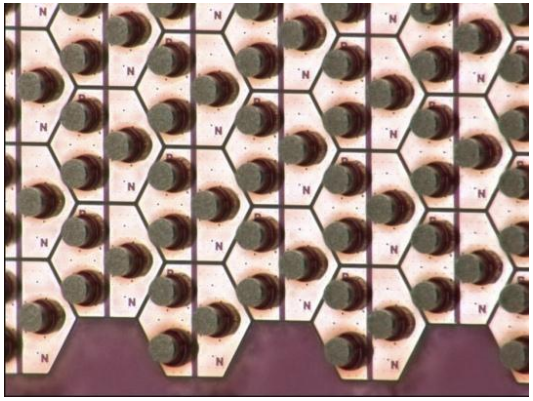
F) Second deep etch defining the cell and 2nd wet etch to suspend the cell



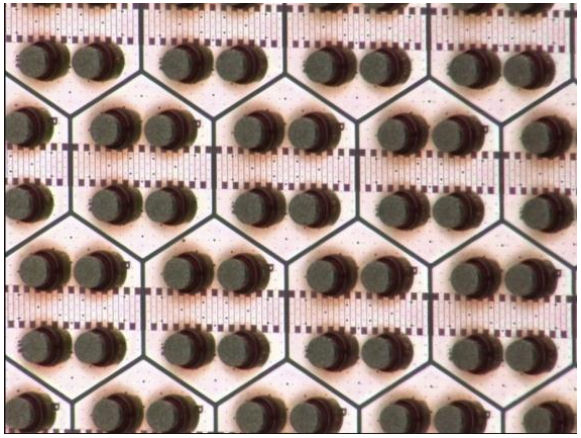


Assembly

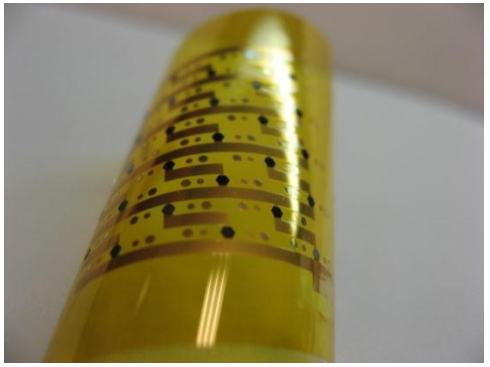


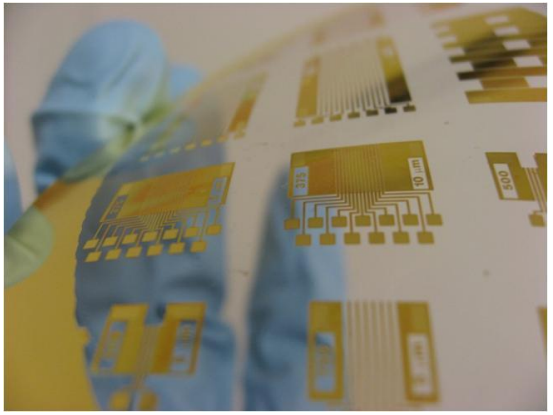


copper/solder bumps



flex receiver substrate (with cells)



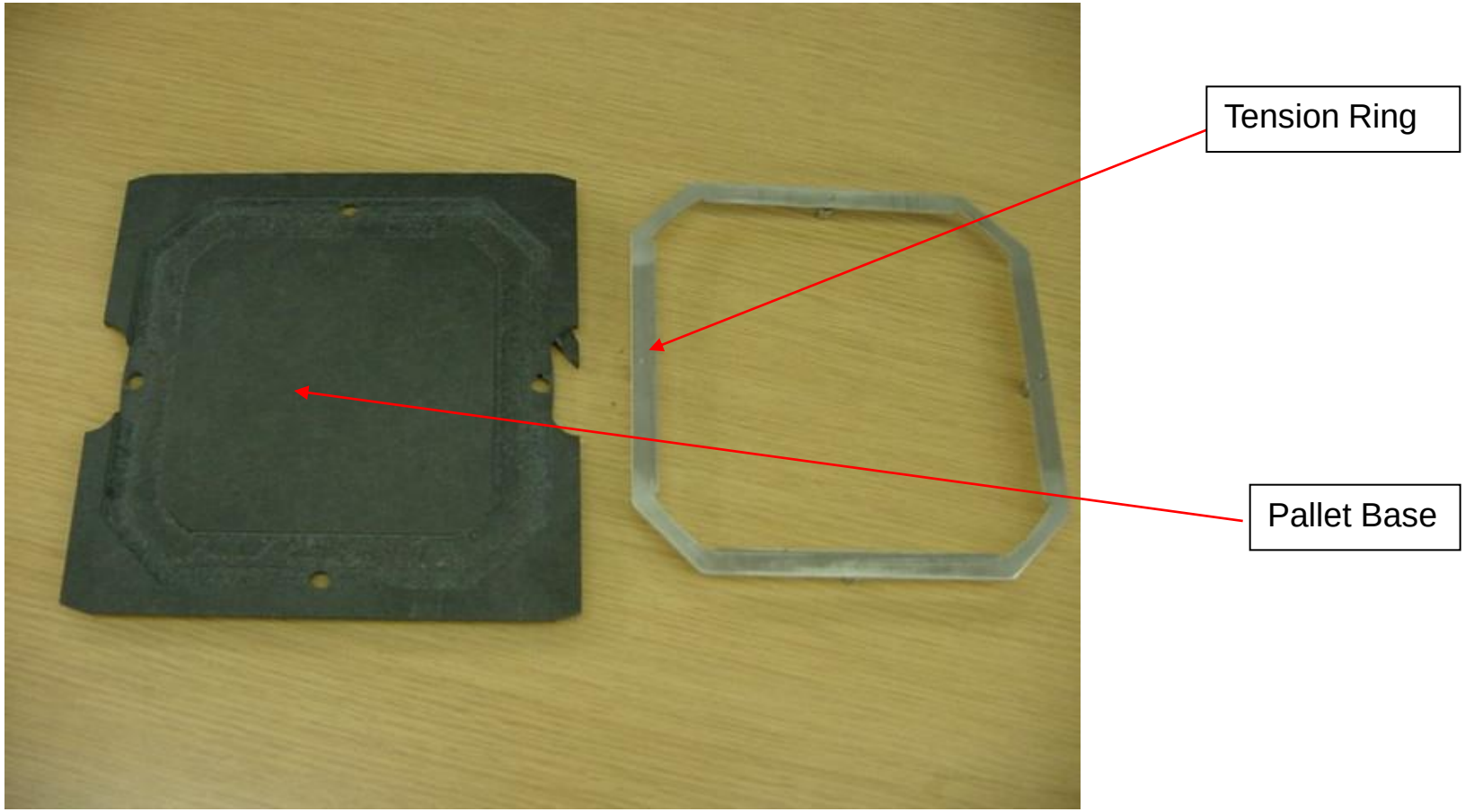


Corning® Willow™ Glass

CORNING

Solar Cell Assembly Process

Custom Tooling for Flex Circuit Assembly Down to 12um Thick Films



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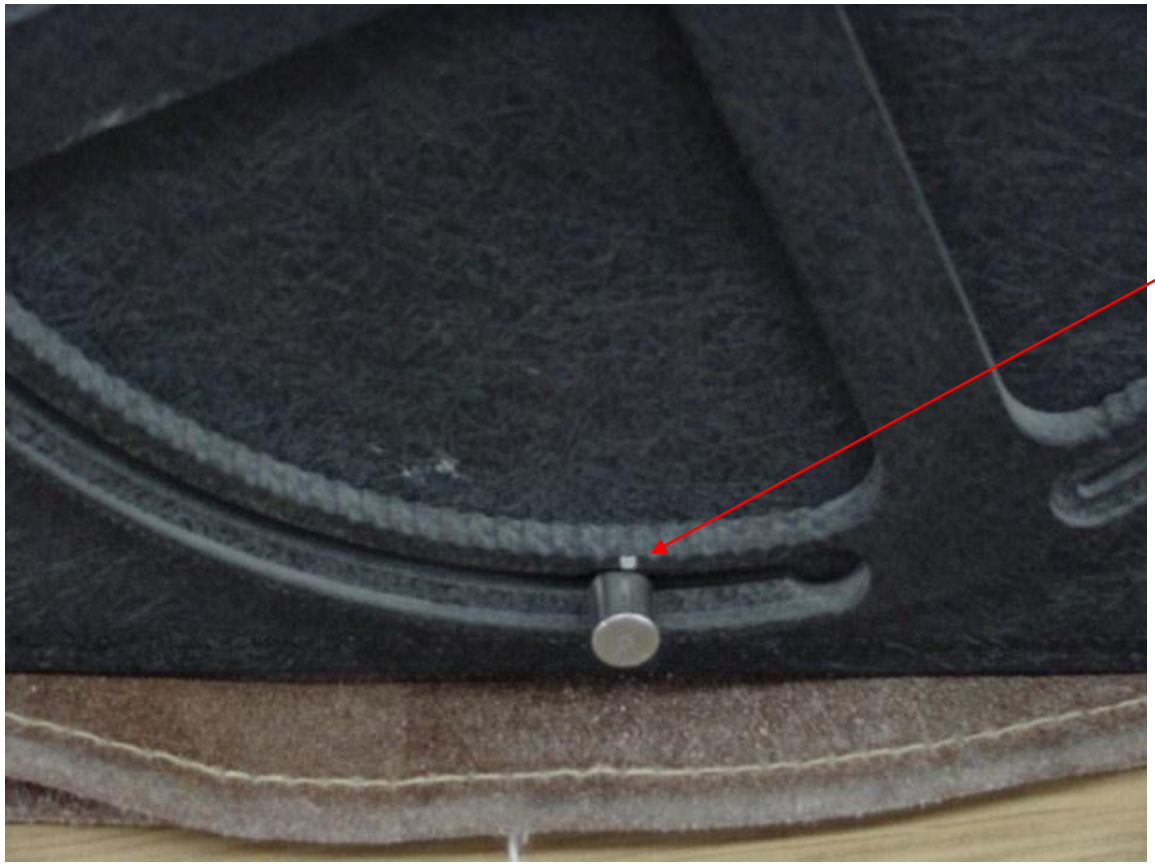

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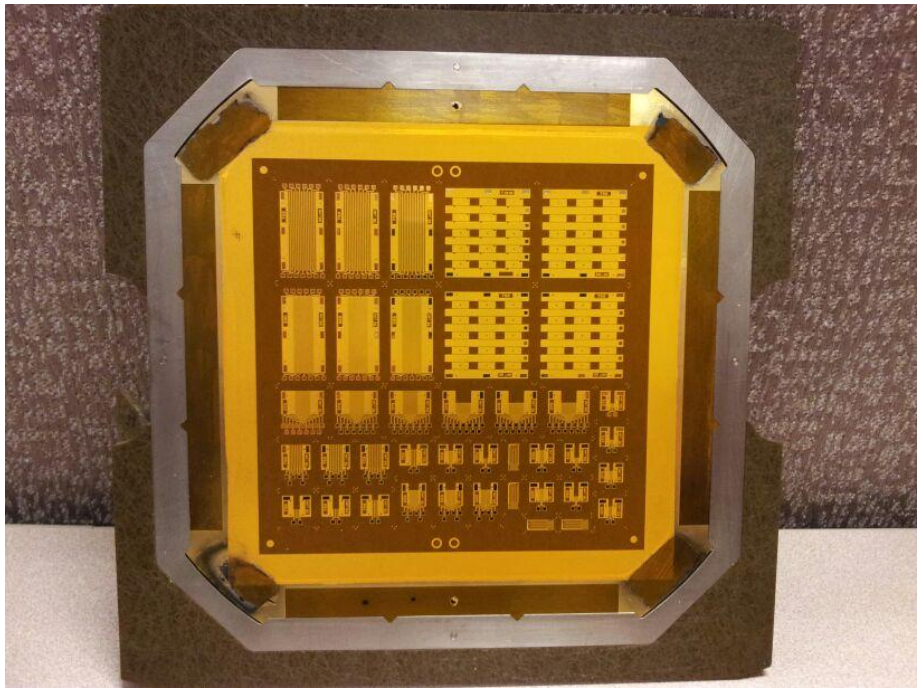
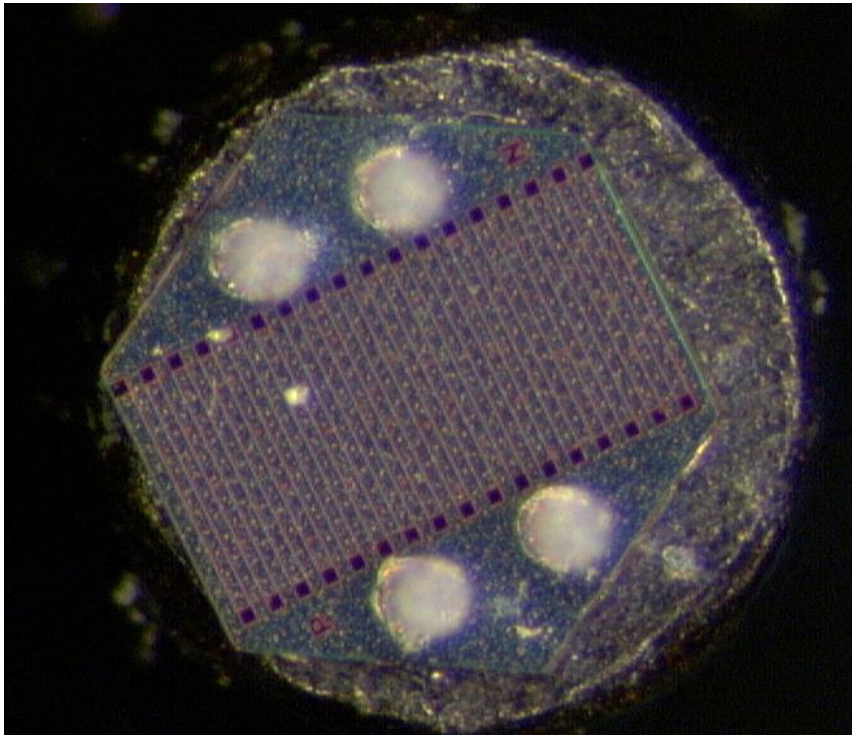


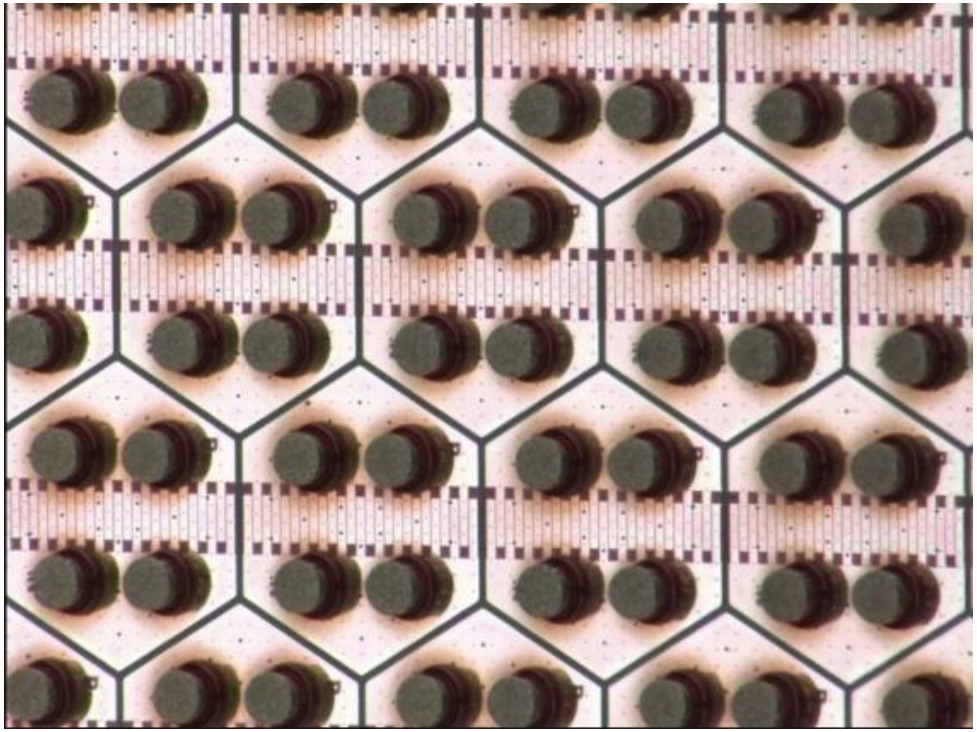
Solar Cell Assembly Process

Two Different Solar Cell Configurations Have Been Assembled To Date

Single “Released” Cells @ 20um Thick



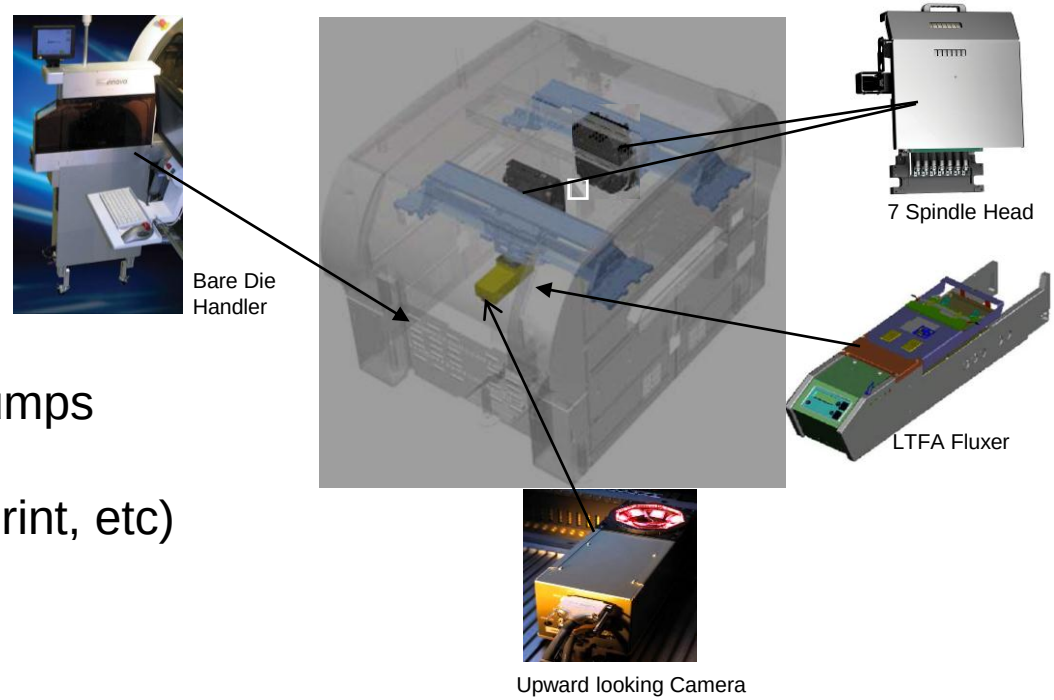
Ganged “Non-released” Cells



Solar Cell Assembly Process

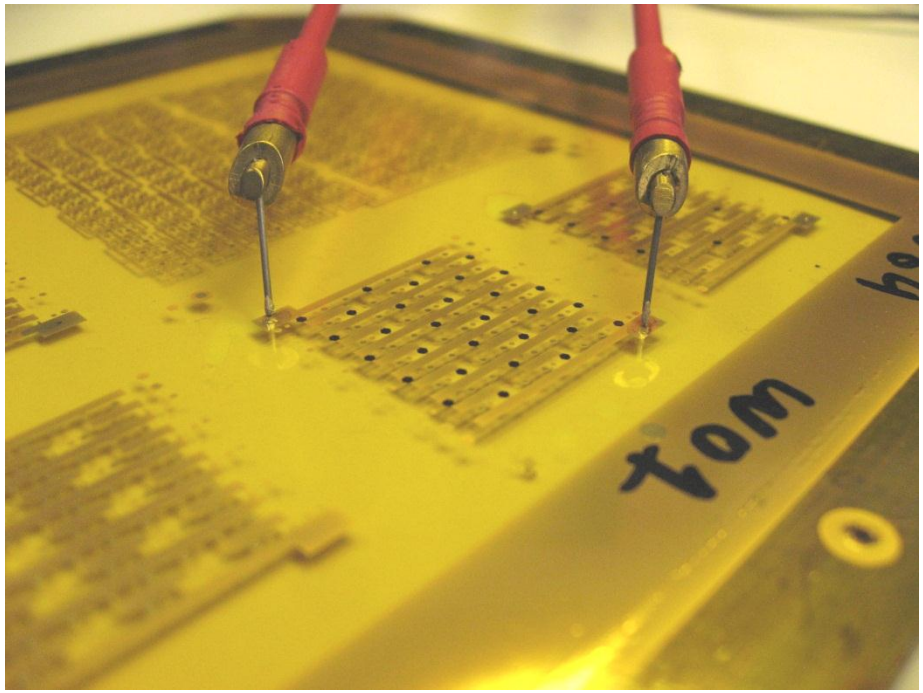
Assembly Process Flow

- Pick up of solar cell
- Vision imaging of Copper/solder bumps
- Flux application (dip, pin transfer, print, etc)
- Placement of solar cells
- Mass reflow of assembly
- Release of “backer” for “ganged” cell applications



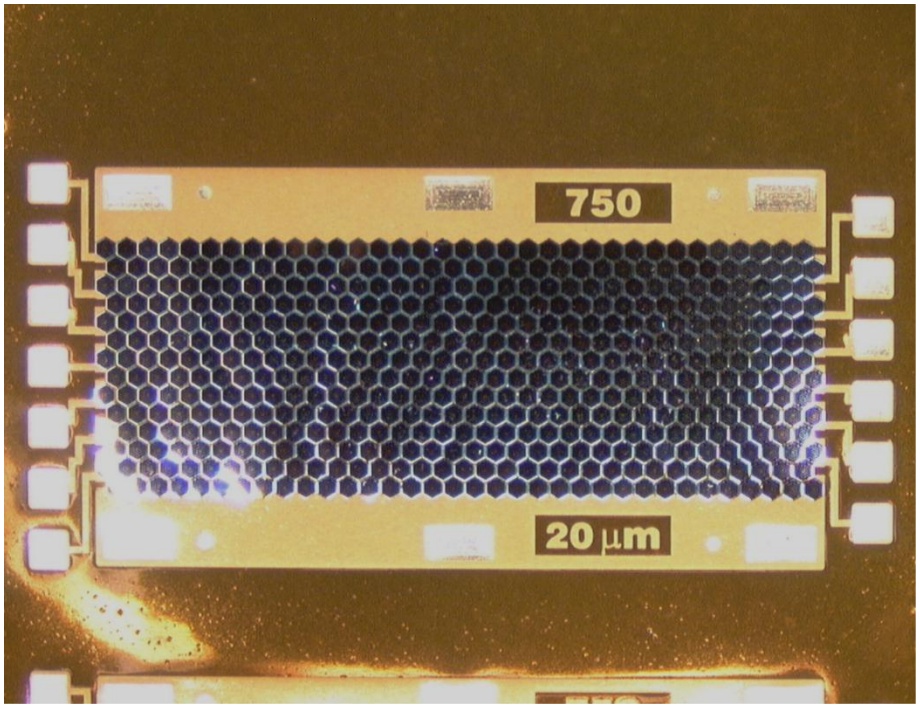
Solar Cell Assembly Process

Mounted Single Solar Cells



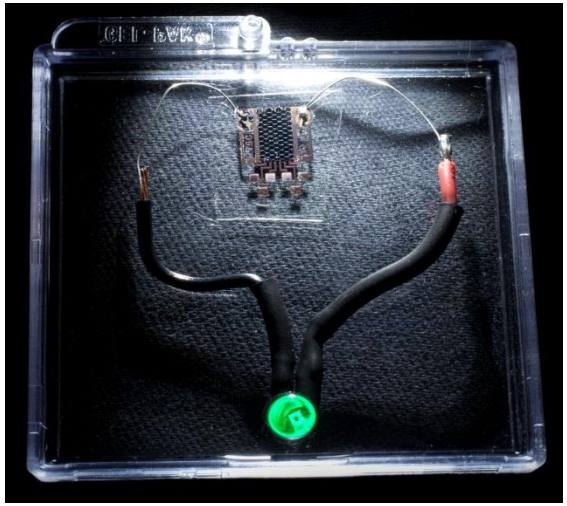
Solar Cell Assembly Process

Mounted “Ganged” Solar Cells

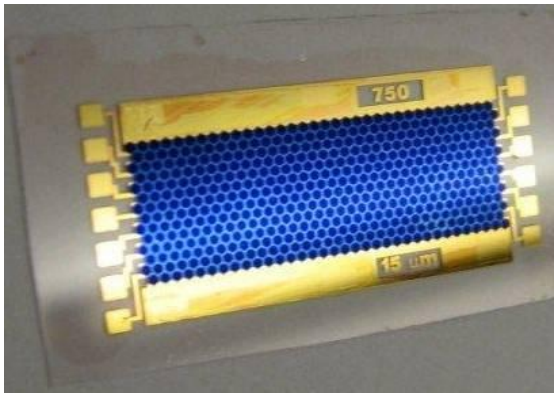


Prototype Examples

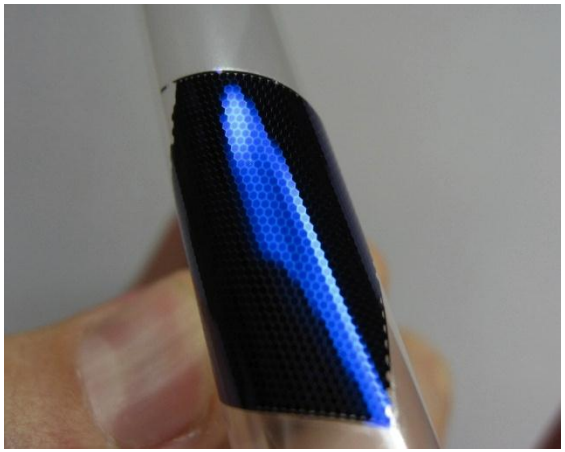
750um cell flexible prototypes on glass and polymer substrates



Corning® Willow™ Glass Substrate



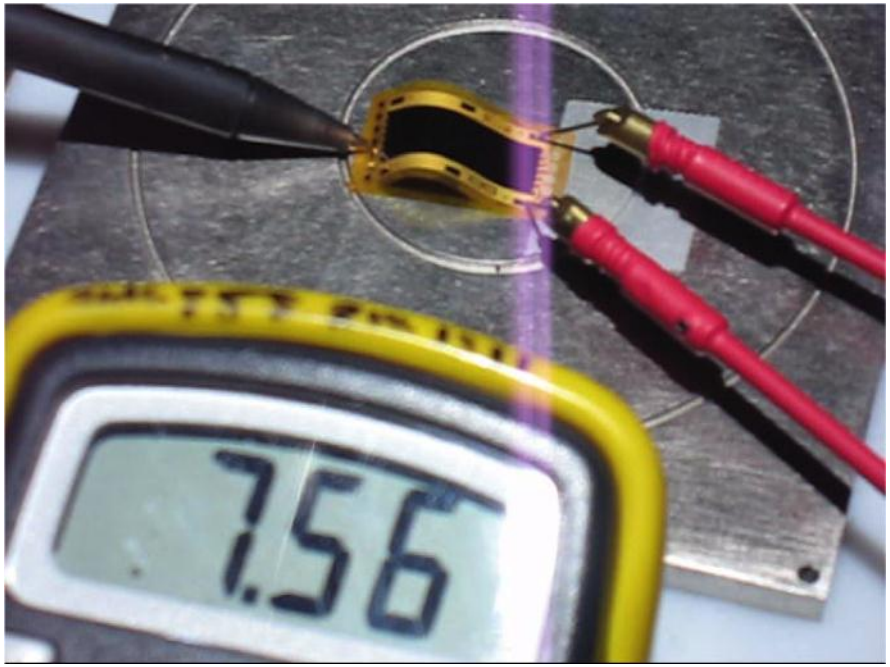
Polymer Substrate



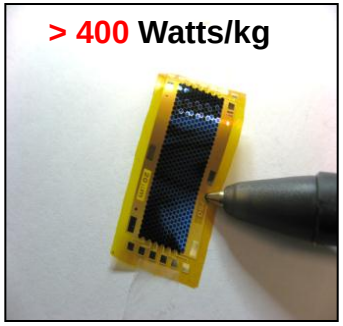
Prototype Examples

750um cell flexible prototype on polymer substrate

- Bend radius < 2mm without damage/degradation.
- <100um as assembled.
- Demonstrated 13.8% array efficiency with single junction Si
  - >20% Si target
  - >35% multi-junction
- >1000 W/kg target (single junction).
- 10 kW array stowable into poster tube (“kW-in-a-can”).
- 10s of W in a pencil dimension tube.



MEPV

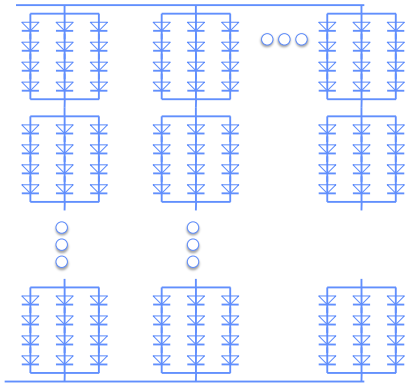


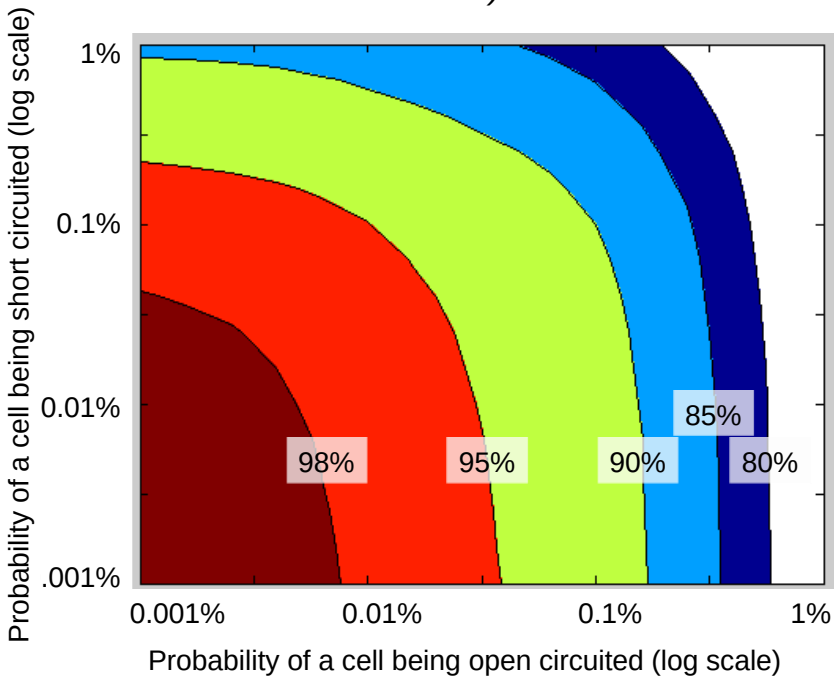
The Competition

New Functionality

- Better performance in partial shading without the need for bypass protection diodes.
- Inherently robust (open/short, damage resistance).
- High-voltage DC (600 – 1000 V) in minimal footprint (5cm x 5cm).
- Integrated power management for on-the-fly optimization, voltage selection, state-of-health monitoring, logging.
- Reduced mechanical stresses and fatigue due to smaller cell/interconnect size.
- Integration of III-V layers/cells, independently connected junctions for highest performance possible.
- …

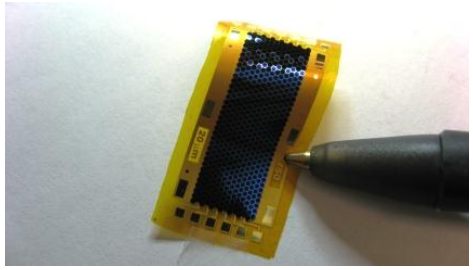
With thousands of solar cells per square meter available, increasing levels of series-parallel-series-parallel connection networks of solar cells allow for improved performance (contour plot illustrates relative efficiency of module with different percentages of opens or shorts within the module).



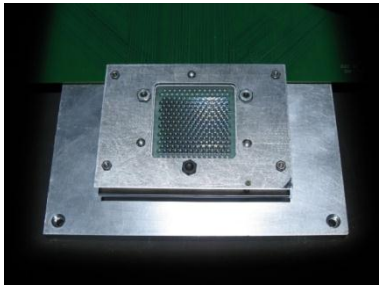


Broad Application: Power Markets

MEPV solar cells can be integrated into flexible and/or moldable polymer substrates for high-efficiency and flexible or 3D conformal applications



MEPV solar cells can be built into a thin concentrator module and sold for solar power applications



Value of Power

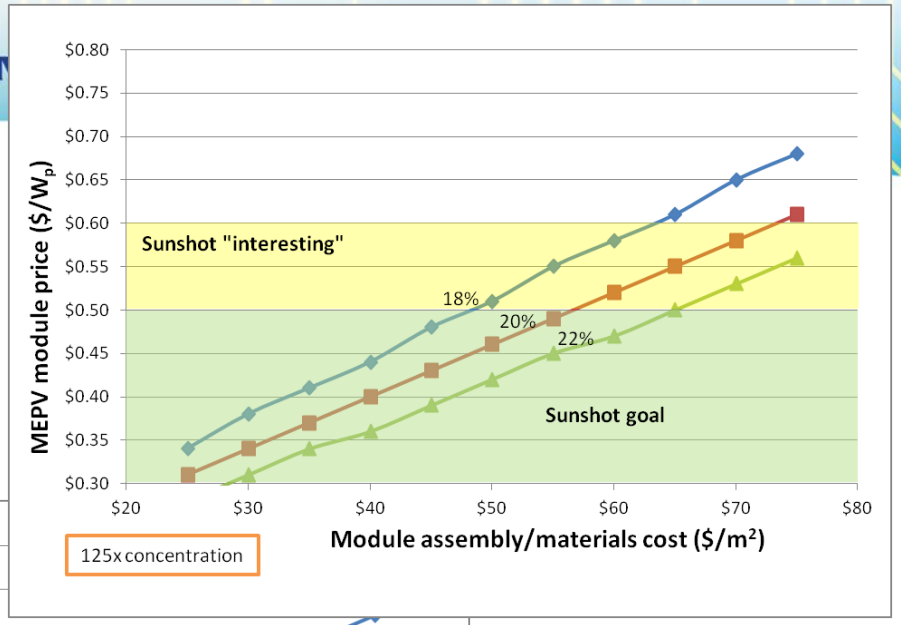
- Space (500 kW/yr) $500 – 1000/W$_{peak}$
- Defense (~100 MW/yr) $50/W$_{peak}$
- Consumer-Logistic (>100MW/yr) $50/W$_{peak}$
- Consumer-Mobile (AA battery = $100-200/kWh)
- Residential Solar Power (>100 GW/year) $0.10 – 0.20/kWh = ~$2/W$_{peak}$
- Commercial (>100 GW/yr) $0.10 – 0.20/kWh = ~$2/W$_{peak}$
- Utility (>100 GW/yr) $0.5 – 0.10/kWh = ~$1/W$_{peak}$

Market Size

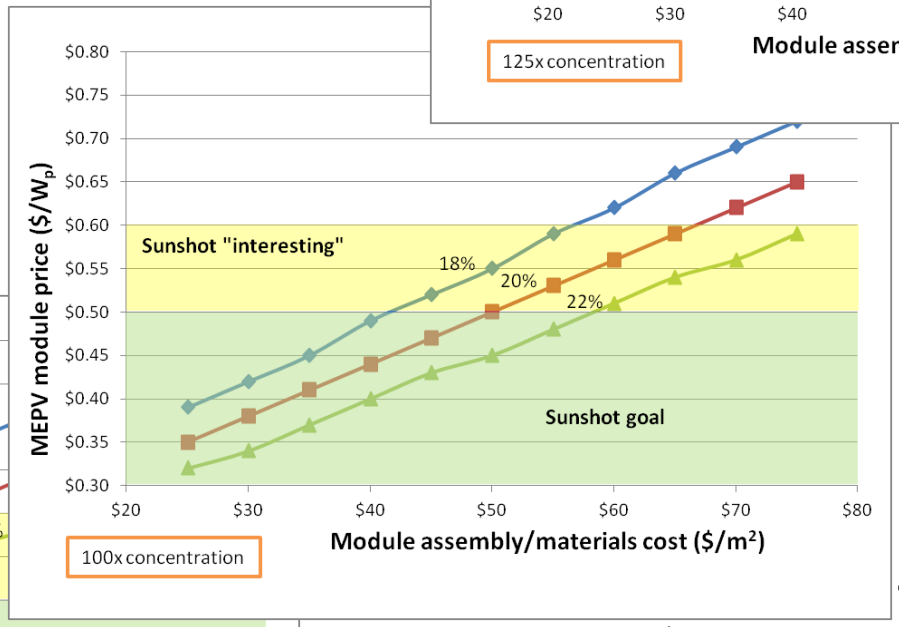
MEPV Cost Models

18% margin
200mm wafers

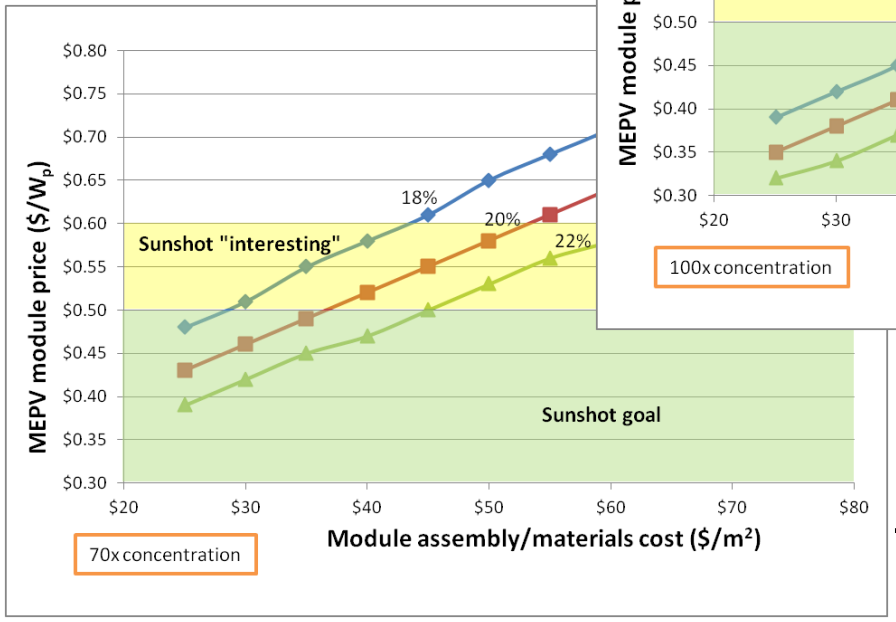
$100/8" wafer cell fab cost



125x



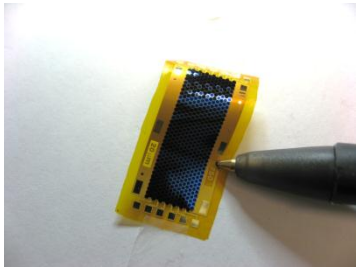
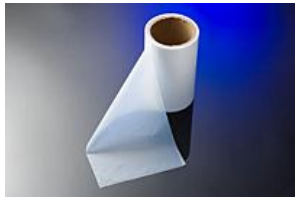
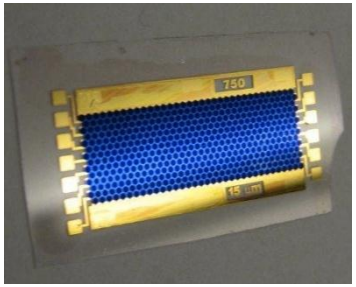
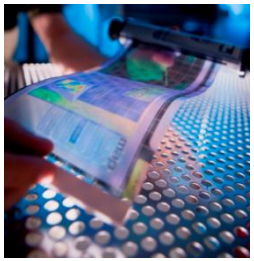
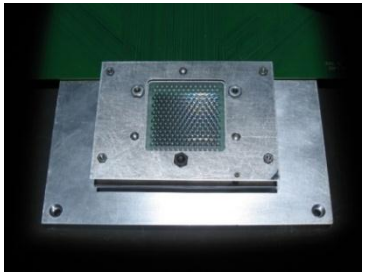
100x



70x

BOS costs are another $0.50/W$_p$ – MEPV approach has the potential to reduce those costs as well (integrated power management, easier install, cheaper trackers, etc.)

Where will we be in 2 years?

Now	In 2 Years	Next Steps
	 **Highly flexible prototype with 20% efficient, >1000 Watts/kg**	**Identify** defense systems integrators, for high margin, differentiated applications of MEPV in a flexible format
	 **Small prototype integrated system for charging mobile devices**	**Identify** electronics manufacturers for partnering opportunities, focused on mobile charging/energy harvesting applications. Requires either flexible or conformal MEPV capabilities with high-efficiency.
	 **Low-Cost, High-Efficiency MEPV concentrator prototype**	**Continue** working with solar companies: both supply chain and system integrators

3DIC / Hybrid Integration

- Same technology base enables hybrid integration of dissimilar materials/processes with high throughput and high yield.
- Additional functionality integrated at chip or assembly level.
- Multiple assembly substrates possible.
- Current 3DIC approaches have significant issues with thin wafer handling, which is eliminated with this approach.

Acknowledgements

Sandia: Gregory Nielson, Jose Luis Cruz-Campa, Bradley Jared, Paul Resnick, Ben Anderson, Bill Sweatt, Tony Lentine, Dan Sauvignon, Vipin Gupta, Jeff Nelson, Carlos Sanchez, Judi Lavin, Peggy Clews, Jonathan Wierer, Jeff Cederberg, Bob Biefeld, Willie Luk, Igal Brener, Anna Tauke-Pedretti, Jennifer Granata

Collaborators: Paul Sharps, Dan Aiken (Emcore), (Universal Instruments), Mike Haney (UD), Sean Garner, Boh Ruffin (Corning)

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